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(54) Title: HIGH PERFORMANCE INTEGRATED CIRCUIT PACKAGE

## (57) Abstract

A high performance integrated circuit package (10) placed on a printed circuit (PC) board (56) and having a first dielectric layer. On top of this first dielectric layer a metallized die pad (22) and a first metal ring (38a), surrounding this metallized die pad, are positioned. The metallized die pad and the first metal ring electrically couple to the PC board to receive respectively a first power supply signal and a second power supply signal. An integrated circuit die (12) is then affixed to the metallized die pad. This integrated circuit die (12) has a first power supply signal bond pad (28, 30) and a second power supply signal bond pad (33, 34), which respectively are coupled to the metallized die pad and the first metal ring. Consequently, the metallized die pad and the first metal ring operate as a first power supply plane and a second power supply plane coupling the first and second power supply signals coming from the PC board to the first and second power supply signal bond pads on the integrated circuit die.

